

Maximum Ratings @T_A = +25°C unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	20	V
Gate-Source Voltage			V _{GSS}	±12	V
Continuous Drain Current (Note 6)	Steady State	T _A = +25°C	I _D	9.5	A
		T _A = +85°C		7.1	
Pulsed Drain Current (Note 7)			I _{DM}	30	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	1.28	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 6)	R _{θJA}	99.3	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics @T_A = +25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	-	-	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	-	-	1.0	μA	V _{DS} = 20V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	-	-	±10	μA	V _{GS} = ±12V, V _{DS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(th)}	0.5	1.0	1.5	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(on)}	-	11	16	mΩ	V _{GS} = 4.5V, I _D = 9.4A
			17	23		V _{GS} = 2.5V, I _D = 8.3A
Forward Transfer Admittance	Y _{fs}	-	17	-	S	V _{DS} = 5V, I _D = 9.4A
Diode Forward Voltage	V _{SD}	-	0.7	1.2	V	V _{GS} = 0V, I _S = 1.3A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C _{iss}	-	1149	-	pF	V _{DS} = 10V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	-	157	-	pF	
Reverse Transfer Capacitance	C _{rss}	-	142	-	pF	
Gate Resistance	R _g	-	1.51	-	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge (V _{GS} = 4.5V)	Q _g	-	11.6	-	nC	V _{GS} = 4.5V, V _{DS} = 10V, I _D = 9.4A
Total Gate Charge (V _{GS} = 10V)	Q _g	-	26	-	nC	
Gate-Source Charge	Q _{gs}	-	2.7	-	nC	
Gate-Drain Charge	Q _{gd}	-	3.4	-	nC	
Turn-On Delay Time	t _{D(on)}	-	11.67	-	ns	V _{DD} = 10V, V _{GS} = 4.5V, R _{GEN} = 6Ω, I _D = 1A
Turn-On Rise Time	t _r	-	12.49	-	ns	
Turn-Off Delay Time	t _{D(off)}	-	35.89	-	ns	
Turn-Off Fall Time	t _f	-	12.33	-	ns	

- Notes:
6. Device mounted on FR-4 PCB, with minimum recommended pad layout.
 7. Repetitive rating, pulse width limited by junction temperature.
 8. Short duration pulse test used to minimize self-heating effect.
 9. Guaranteed by design. Not subject to production testing.

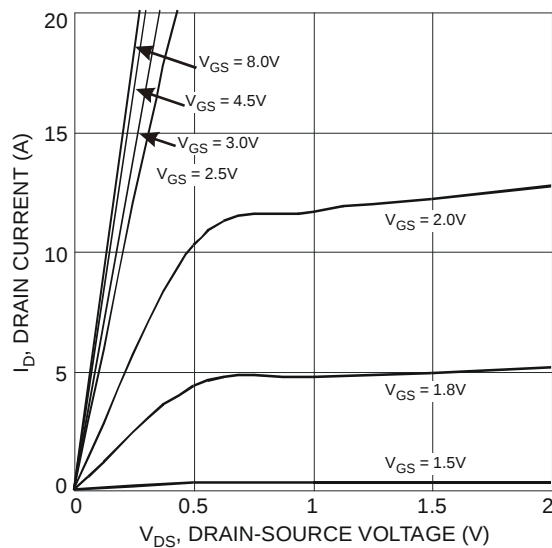


Fig. 1 Typical Output Characteristic

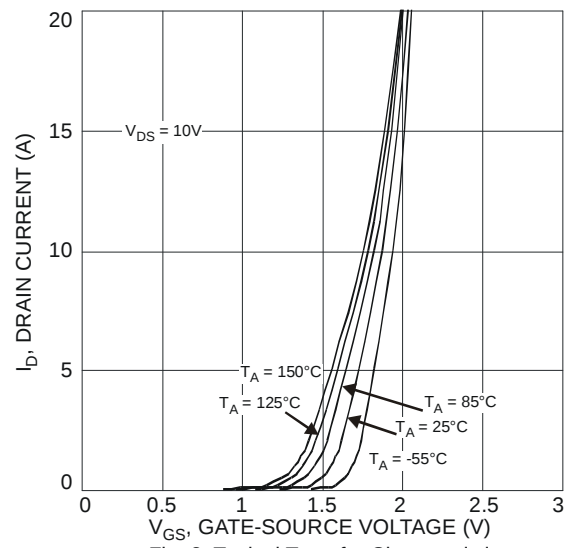


Fig. 2 Typical Transfer Characteristic

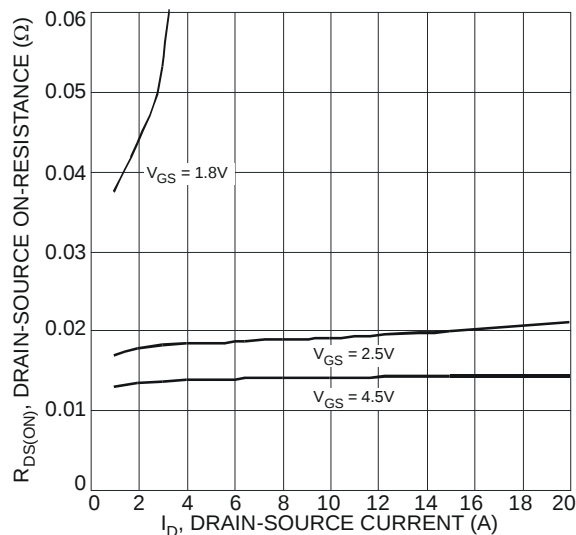


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

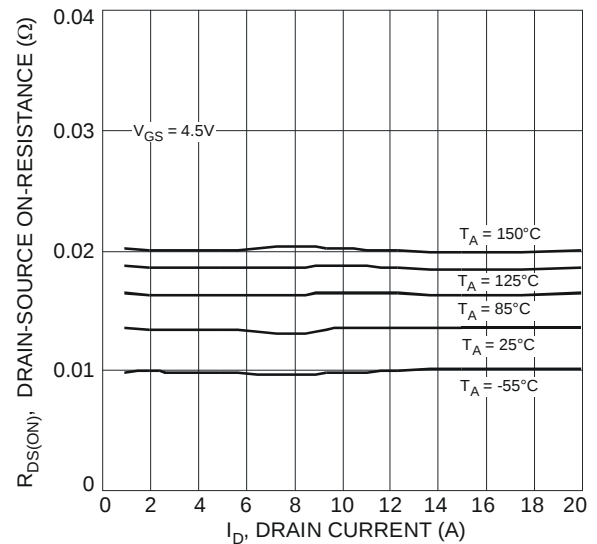


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

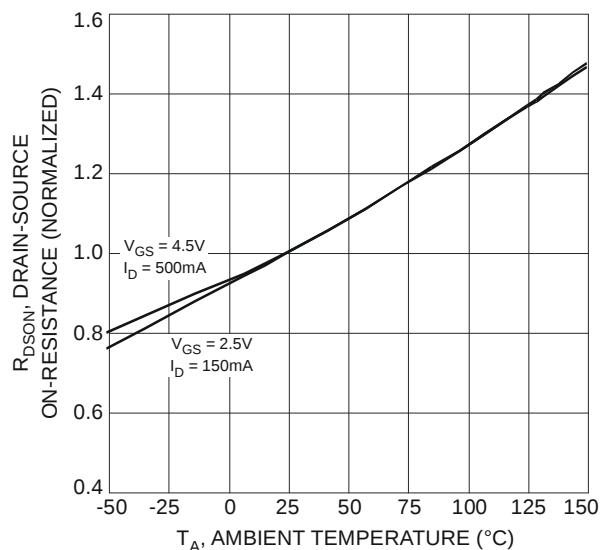


Fig. 5 On-Resistance Variation with Temperature

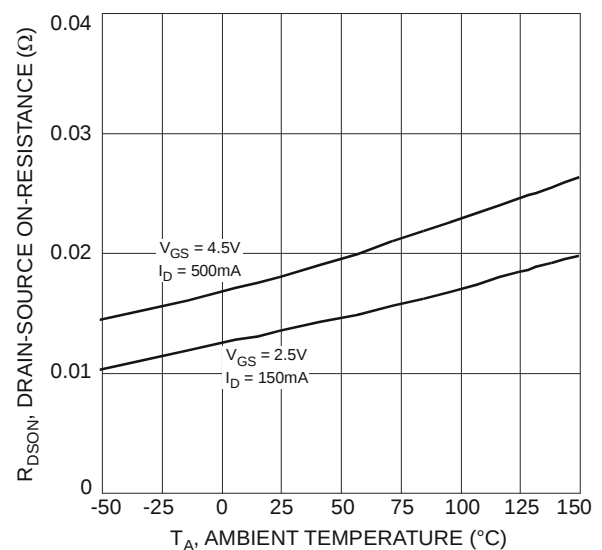


Fig. 6 On-Resistance Variation with Temperature

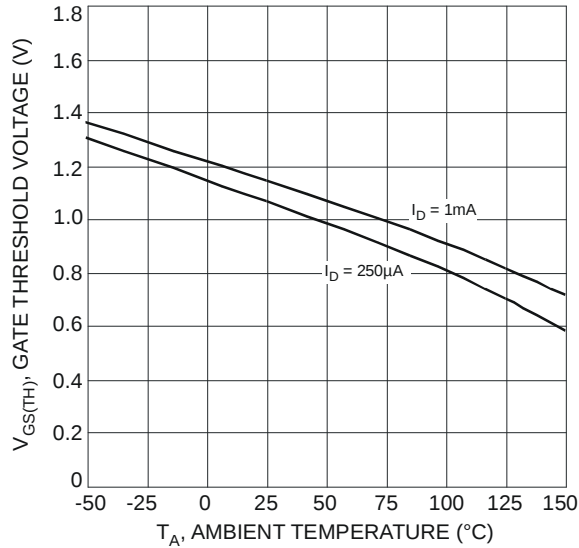


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

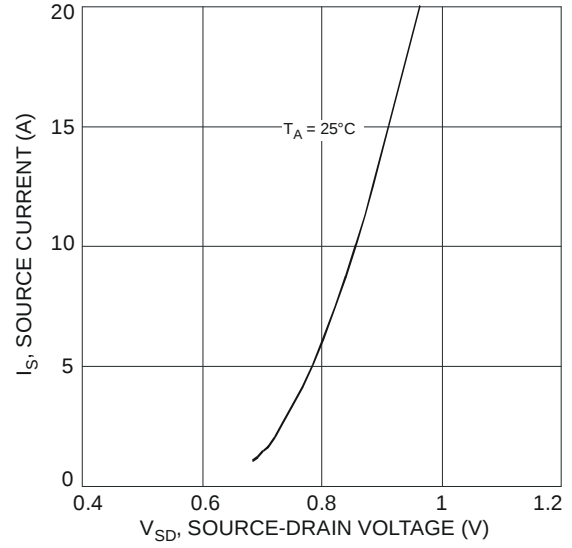


Fig. 8 Diode Forward Voltage vs. Current

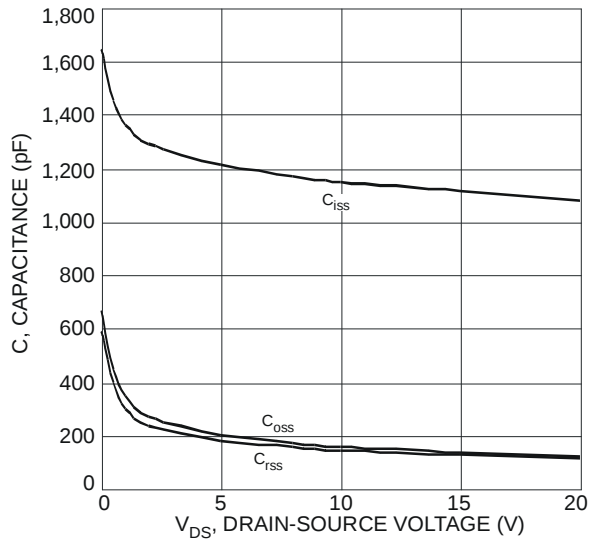


Fig. 9 Typical Total Capacitance

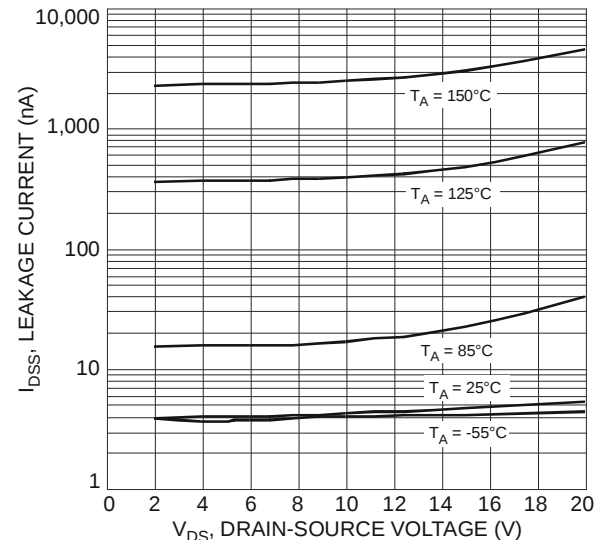


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

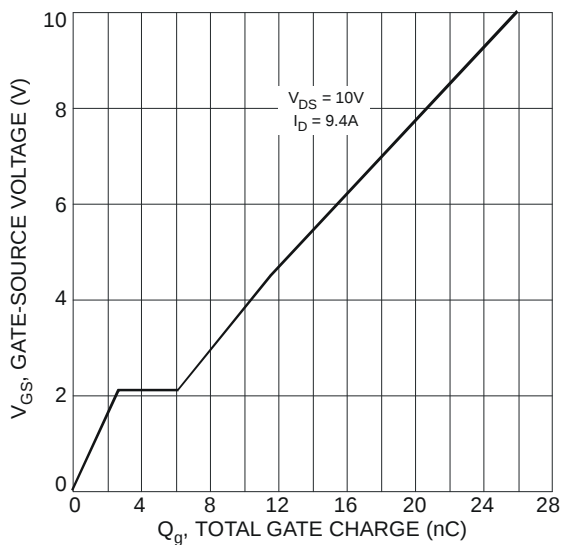


Fig. 11 Gate-Source Voltage vs. Total Gate Charge

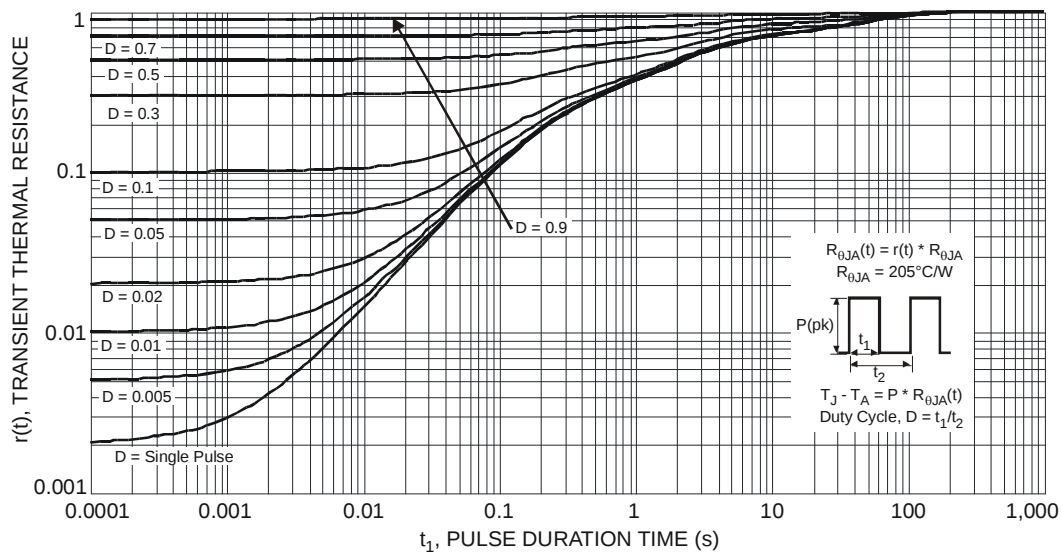
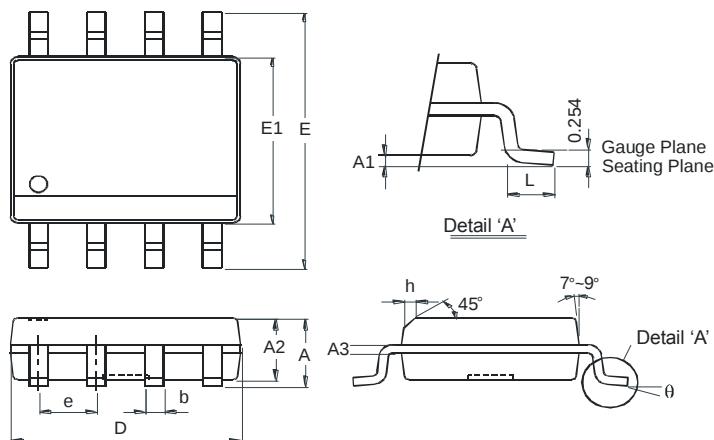


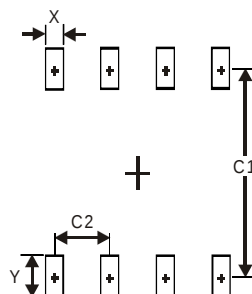
Fig. 12 Transient Thermal Response

Package Outline Dimensions

 Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.


SO-8		
Dim	Min	Max
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	-	0.35
L	0.62	0.82
θ	0°	8°
All Dimensions in mm		

Suggested Pad Layout

 Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.


Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

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